



MOTOROLA

Dual Binary to 4-Line Decoder (High)

ELECTRICALLY TESTED PER:
MPG 10572

The 10572 is a binary coded 2 line to dual 4 line decoder with selected outputs high. With either $\bar{E}_0$ or $\bar{E}_1$ low, the corresponding selected 4 outputs are low. The common enable $\bar{E}$, when high, forces all outputs low.

- 445 mW Max/Pkg (No Load)
- $t_{pd} = 4.0$ ns typ
- $t_r, t_f = 2.0$ ns typ (20% - 80%)

FUNCTION	PIN ASSIGNMENTS			BURN-IN (CONDITION C)
	DIL	FLATS	LCC	
V_{CC1}	1	5	2	GND
$\bar{E}_1$	2	6	3	GND
Q13	3	7	4	51 Ω to V_{TT}
Q12	4	8	5	51 Ω to V_{TT}
Q11	5	9	7	51 Ω to V_{TT}
Q10	6	10	8	51 Ω to V_{TT}
B	7	11	9	OPEN
V_{EE}	8	12	10	V_{EE}
A	9	13	12	OPEN
Q03	10	14	13	51 Ω to V_{TT}
Q02	11	15	14	51 Ω to V_{TT}
Q01	12	16	15	51 Ω to V_{TT}
Q00	13	1	17	51 Ω to V_{TT}
$\bar{E}_0$	14	2	18	GND
$\bar{E}$	15	3	19	OPEN
V_{CC2}	16	4	20	GND

BURN - IN CONDITIONS:

$V_{TT} = -2.0$ V MAX/ -2.2 V MIN

$V_{EE} = -5.7$ V MAX/ -5.2 V MIN

Military 10572

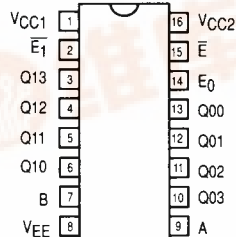


AVAILABLE AS

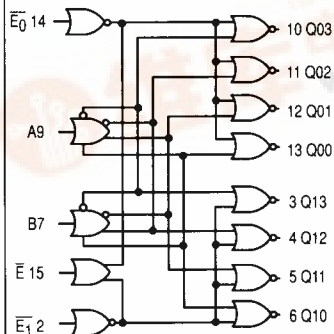
- 1) JAN: N/A
 - 2) SMD: N/A
 - 3) 883: 10572/BXAJC
- X = CASE OUTLINE AS FOLLOWS:

PACKAGE: CERDIP: E
CERFLAT: F
LCC: 2

The letter "M" appears before
the slash on LCC.



LOGIC DIAGRAM



3



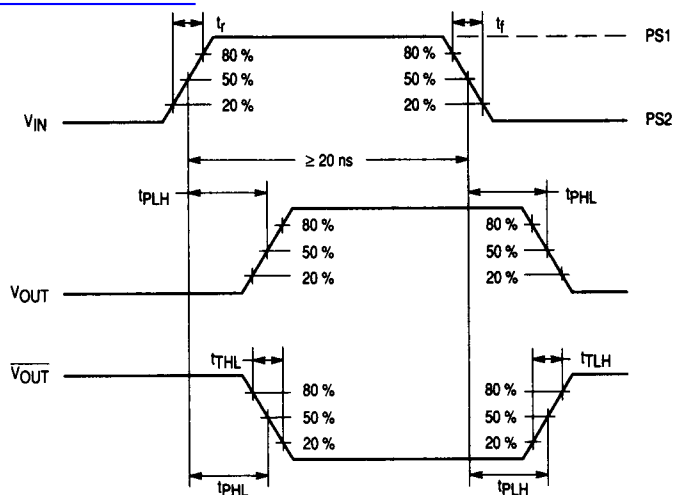
3

查询"10572/BEA JC"供应商

Ø = Don't Care



[查询"10572/BEAJC"供应商](#)



NOTES

1. Pulse generator must be capable of rise and fall times of $2.0 \text{ ns} \pm 0.2 \text{ ns}$.
2. 2:1 divider may be used.
3. Length of Coax_A and Coax_B should be equal for equal time delay.
4. $t_r = t_f = 2.0 \text{ ns} \pm 0.2 \text{ ns}$ (20% to 80%)
5. $R_L = 50 \Omega$ resistor in series with 50Ω coax constituting the 100Ω load.
6. Unused outputs should be loaded 100Ω to ground

NOTES

V_{IN} has the following characteristics:

- a) $PW \geq 20 \text{ ns}$.
- b) $f_{IN} = 1.0 \text{ MHz}$.
- c) t_r and $t_f = 2.0 \text{ ns} \pm 0.2 \text{ ns}$. (20% - 80%)

Figure 2. Switching Test Circuit Waveforms

10572 QUIESCENT LIMIT TABLE *

* ELECTRICAL CHARACTERISTICS

Each MECL 10K series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 100 Ω resistor to - 2.0 volts.

Test Temperature	Test Voltage Values (Volts)						
	V _{IH}	V _{IL}	V _{IH1}	V _{IL1}	PS ₁	PS ₂	VEEL
T _A = 25 °C	- 0.78	- 1.85	- 1.105	- 1.475	+ 1.11	+ 0.31	- 5.2
T _A = 125 °C	- 0.63	- 1.82	- 1.000	- 1.400	+ 1.24	+ 0.36	- 5.2
T _A = - 55 °C	- 0.88	- 1.92	- 1.255	- 1.510	+ 1.01	+ 0.28	- 5.2

Symbol	Parameter	Limits						Units	TEST VOLTAGE APPLIED TO PINS BELOW									
		+ 25 °C		+ 125 °C		- 55 °C			Pinouts referenced are for DIL package, check Pin Assignments V _{CC} = 0 V, Output Load = 100 Ω to - 2.0 V									
		Min	Max	Min	Max	Min	Max		V _{IH}	V _{IL}	V _{IH1}	V _{IL1}	V _{EE}	V _{CC}	P. U. T.			
V _{OH}	High Output Voltage	- 0.93	- 0.78	- 0.825	- 0.63	- 1.08	- 0.88	V	2, 7, 9, 14			8	1, 16	3 - 6, 10 - 13				
V _{OL}	Low Output Voltage	- 1.85	- 1.62	- 1.82	- 1.545	- 1.92	- 1.635	V	15			8	1, 16	3 - 6, 10 - 13				
V _{OL1}	Low Output Voltage	- 1.85	- 1.60	- 1.82	- 1.525	- 1.92	- 1.635	V	2, 7, 9, 14		2, 7, 9, 14	8	1, 16	3 - 6, 10 - 13				
V _{OH1}	High Output Voltage	- 0.95	- 0.78	- 0.845	- 0.63	- 1.10	- 0.88	V	2, 7, 9, 14		2, 7, 9, 14	8	1, 16	3 - 6, 10 - 13				
I _{IH1}	Input Current High		220		375		375	µA	2, 7, 9, 14, 15			8	1, 16	2, 7, 9, 14, 15				
I _{IL}	Input Current Low	0.5		0.3		0.5		µA				8	1, 16	2, 7, 9, 14, 15				
I _{EE}	Power Supply Drain Current	- 77		- 85		- 85		mA				8	1, 16	8				

10572 QUIESCENT LIMIT TABLE *

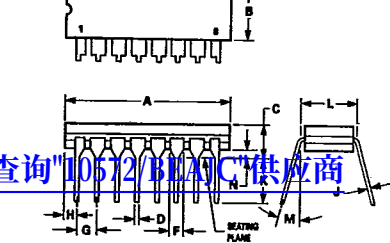
* ELECTRICAL CHARACTERISTICS

Each MECL 10K series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 100 Ω resistor to - 2.0 volts.

Test Temperature	Test Voltage Values (Volts)						
	V _{IH}	V _{IL}	V _{IHI}	V _{ILI}	PS ₁	PS ₂	VEEL
T _A = 25 °C	- 0.78	- 1.85	- 1.105	- 1.475	+ 1.11	+ 0.31	- 5.2
T _A = 125 °C	- 0.63	- 1.82	- 1.000	- 1.400	+ 1.24	+ 0.36	- 5.2
T _A = - 55 °C	- 0.88	- 1.92	- 1.255	- 1.510	+ 1.01	+ 0.28	- 5.2

Symbol	Parameter	Limits								Units	TEST VOLTAGE APPLIED TO PINS BELOW					
		+ 25 °C				+ 125 °C					Pinouts referenced are for DIL package, check Pin Assignments V _{CC} = 2.0 V, Output Load = 100 Ω to GND					
		Subgroup 9		Subgroup 10		Subgroup 11										
		Min	Max	Min	Max	Min	Max	V _{IN}	V _{OUT}		V _{CC}	VEEL	PS1	P. U. T.		
t _{TLH}	Rise Time	1.1	3.3	1.0	3.9	1.0	3.6	ns	2, 7, 9, 14, 15	3 - 6, 10 - 13	1, 16	8	2, 7, 9, 14	3 - 6, 10 - 13		
t _{FHL}	Fall Time	1.1	3.3	1.0	3.9	1.0	3.6	ns	2, 7, 9, 14, 15	3 - 6, 10 - 13	1, 16	8	2, 7, 9, 14	3 - 6, 10 - 13		
t _{PLH}	Propagation Delay	1.5	6.0	1.2	7.0	1.3	6.5	ns	2, 7, 9, 14, 15	3 - 6, 10 - 13	1, 16	8	2, 7, 9, 14	3 - 6, 10 - 13		
t _{PHL}	Propagation Delay	1.5	6.0	1.2	7.0	1.3	6.5	ns	2, 7, 9, 14, 15	3 - 6, 10 - 13	1, 16	8	2, 7, 9, 14	3 - 6, 10 - 13		

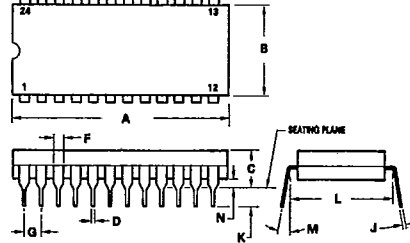
查询"10512/BJ/C"供应商



DIM	MIN	MAX	MIN	MAX
A	19.05	19.81	0.750	0.780
B	6.22	6.98	0.245	0.275
C	4.06	5.08	0.160	0.200
D	0.38	0.51	0.015	0.020
E	1.40	1.65	0.055	0.065
F	2.54 BSC		0.100 BSC	
G	0.51	1.14	0.020	0.045
H	0.20	0.30	0.008	0.012
I	3.18	4.06	0.125	0.160
J	7.37	7.87	0.290	0.310
K	—	15°	—	15°
L	0.51	1.02	0.020	0.040

NOTES:

- LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
- PACKAGE INDEX: NOTCH IN LEAD NOTCH IN CERAMIC OR INK DOT.
- DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.

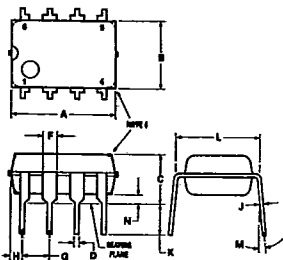


DIM	MIN	MAX	MIN	MAX
A	31.24	32.77	1.230	1.290
B	12.70	15.49	0.500	0.610
C	4.06	5.08	0.160	0.200
D	0.41	0.51	0.016	0.020
E	1.27	1.52	0.050	0.060
F	2.54 BSC		0.100 BSC	
G	0.20	0.30	0.008	0.012
H	3.18	4.06	0.125	0.160
I	15.24 BSC		0.600 BSC	
J	0°	15°	0°	15°
K	0.51	1.27	0.020	0.050

NOTES:

- DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
- LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION. (WHEN FORMED PARALLEL).

P SUFFIX
PLASTIC PACKAGE
CASE 626-04

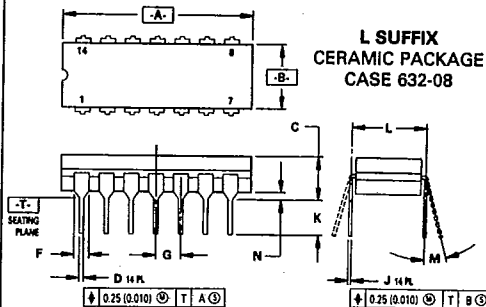


DIM	MIN	MAX	MIN	MAX
A	9.40	10.16	0.370	0.400
B	6.10	6.60	0.240	0.260
C	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
E	1.02	1.52	0.040	0.060
F	2.54 BSC		0.100 BSC	
G	0.76	1.27	0.030	0.050
H	0.20	0.30	0.008	0.012
I	2.92	3.43	0.115	0.135
J	7.62 BSC		0.300 BSC	
K	—	10°	—	10°
L	0.51	0.76	0.020	0.030

NOTES:

- LEAD POSITIONAL TOLERANCE:
 $\phi 0.13 (0.005) \text{ T A } \phi 0.13 \text{ B } \phi$
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
- DIMENSIONS A AND B ARE DATUMS.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

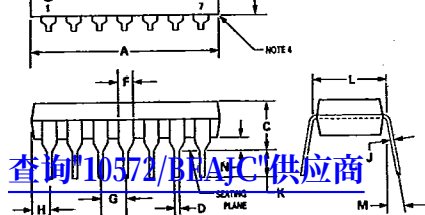
L SUFFIX
CERAMIC PACKAGE
CASE 632-08



DIM	MIN	MAX	MIN	MAX
A	19.05	19.94	0.750	0.785
B	6.23	7.11	0.245	0.280
C	3.94	5.08	0.155	0.200
D	0.39	0.50	0.015	0.020
E	1.40	1.65	0.055	0.065
F	2.54 BSC		0.100 BSC	
G	0.21	0.38	0.008	0.015
H	3.18	4.31	0.125	0.170
I	7.62 BSC		0.300 BSC	
J	0°	15°	0°	15°
K	0.51	1.01	0.020	0.040

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
- DIM F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

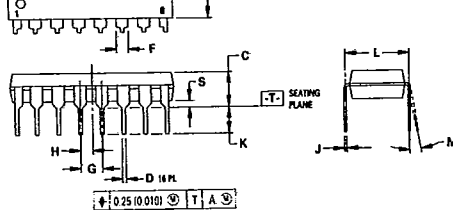


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DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	18.16	19.56	0.715	0.770
B	6.10	6.60	0.240	0.260
C	3.69	4.69	0.145	0.185
D	0.38	0.53	0.015	0.021
E	1.02	1.78	0.040	0.070
F	2.54 BSC		0.100 BSC	
G	1.32	2.41	0.052	0.095
H	0.20	0.38	0.008	0.015
J	2.92	3.43	0.115	0.135
K	7.62 BSC		0.300 BSC	
L	0°	10°	0°	10°
M	0.39	1.01	0.015	0.039

NOTES:

- LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
- DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.
- ROUNDED CORNERS OPTIONAL.

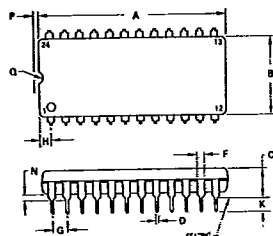


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	18.80	19.55	0.740	0.770
B	6.35	6.85	0.250	0.270
C	3.69	4.44	0.145	0.175
D	0.39	0.53	0.015	0.021
E	1.02	1.77	0.040	0.070
F	2.54 BSC		0.100 BSC	
G	1.27 BSC		0.050 BSC	
H	0.21	0.38	0.008	0.015
J	2.80	2.30	0.110	0.130
K	7.50	7.74	0.295	0.305
L	0°	10°	0°	10°
M	0.51	1.01	0.020	0.040

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.
- ROUNDED CORNERS OPTIONAL.

P SUFFIX PLASTIC PACKAGE CASE 649-03

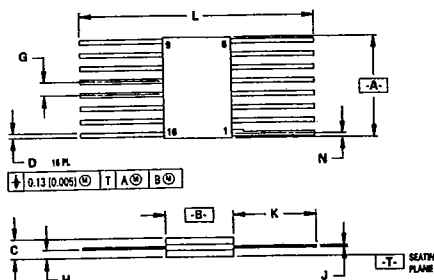


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	31.50	32.13	1.240	1.265
B	13.21	13.72	0.520	0.540
C	4.70	5.21	0.185	0.205
D	0.38	0.51	0.015	0.020
E	1.02	1.52	0.040	0.060
F	2.54 BSC		0.100 BSC	
G	1.65	2.16	0.065	0.085
H	0.20	0.30	0.008	0.012
J	2.92	3.43	0.115	0.135
K	14.99	15.49	0.590	0.610
L	—	10°	—	10°
M	0.51	1.02	0.020	0.040
N	0.13	0.38	0.005	0.015
O	0.51	0.76	0.020	0.030

NOTES:

- LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
- DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.

F SUFFIX CERAMIC PACKAGE CASE 650-05



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.40	9.90	0.370	0.390
B	6.73	6.80	0.245	0.260
C	1.53	2.15	0.060	0.085
D	0.36	0.40	0.014	0.016
E	1.27 BSC		0.050 BSC	
F	0.64	0.01	0.025	0.040
G	0.11	0.17	0.004	0.007
H	6.35	9.39	0.250	0.370
I	18.93	—	0.745	—
J	—	0.50	—	0.020

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION "A" AND "B" ALLOW FOR LID MISALIGNMENT, AND GLASS MENISCUS.
- DIMENSION "H" SHALL BE MEASURED AT THE POINT OF EXIT OF THE LEAD FROM THE BODY.
- LEAD NUMBER 1 IDENTIFIED BY TAB ON LEAD OR DOT ON COVER.
- DIMENSION "J" INCLUDES SOLDER LEAD FINISH.
- LEAD NUMBERS SHOWN FOR REFERENCE ONLY.

查询"10572 BEAC"供应商

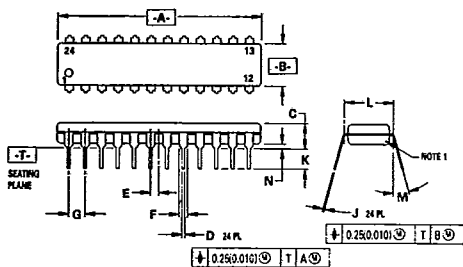
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	0.91	10.92	0.360	0.430
B	6.32	6.39	0.245	0.275
C	4.32	5.06	0.170	0.200
D	0.41	0.51	0.016	0.020
F	1.40	1.65	0.055	0.065
G	2.54 BSC		0.100 BSC	
H	1.14	1.65	0.045	0.065
J	0.20	0.30	0.008	0.012
K	3.18	4.06	0.125	0.160
L	7.37	7.87	0.290	0.310
M	—	15°	—	15°
N	0.51	1.02	0.020	0.040

- NOTES:
- LEADS WITHIN 0.13 mm (0.005) RAD OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
 - DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	22.72	23.24	0.915	0.915
B	6.10	6.60	0.240	0.260
C	3.56	4.57	0.140	0.180
D	0.56	0.56	0.014	0.022
F	1.27	1.78	0.050	0.070
G	2.54 BSC		0.100 BSC	
H	1.02	1.52	0.040	0.060
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

- NOTES:
- POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25mm(0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
 - DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 - DIMENSION B DOES NOT INCLUDE MOLD FLASH.

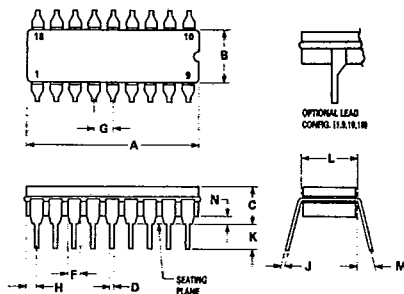
P SUFFIX PLASTIC PACKAGE CASE 724-03



	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	31.25	32.13	1.230	1.265
B	6.35	6.86	0.250	0.270
C	3.69	4.44	0.145	0.175
D	0.38	0.51	0.015	0.020
E	1.27 BSC		0.050 BSC	
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	0.18	0.30	0.007	0.012
J	0.18	0.30	0.007	0.012
K	2.80	3.55	0.110	0.140
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.01	0.020	0.040

- NOTES:
- CHAMFERED CONTOUR OPTIONAL.
 - DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
 - DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1987.
 - CONTROLLING DIMENSION: INCH.

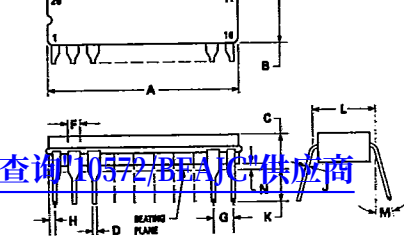
L SUFFIX CERAMIC PACKAGE CASE 726-04



	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	22.75	23.11	0.890	0.910
B	6.10	7.49	0.240	0.295
C	—	5.08	—	0.200
D	0.38	0.53	0.015	0.021
F	1.40	1.78	0.055	0.070
G	2.54 BSC		0.100 BSC	
H	0.51	1.14	0.020	0.045
J	0.20	0.30	0.008	0.012
K	3.18	4.32	0.125	0.170
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

- NOTES:
- LEADS, TRUE POSITIONED WITHIN 0.25 mm (0.010) DIA. AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
 - DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
 - DIM "A" & "B" INCLUDES MENISCUS.
 - "F" DIMENSION IS FOR FULL LEADS. "HALF" LEADS ARE OPTIONAL AT LEAD POSITIONS 1, 9, 10, AND 18.

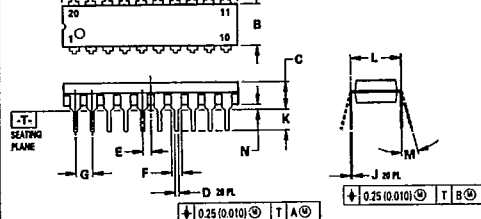
查询 10372 BFA 供应商



DIM	MIN	MAX	MIN	MAX
A	23.88	25.15	0.940	0.990
B	6.80	7.49	0.269	0.295
C	3.81	5.08	0.150	0.200
D	0.38	0.56	0.015	0.022
E	1.40	1.65	0.055	0.065
F	2.54 BSC		0.100 BSC	
G	0.51	1.27	0.020	0.050
H	0.20	0.30	0.008	0.012
J	3.18	4.06	0.125	0.160
K	7.62 BSC		0.300 BSC	
L	0°	15°	0°	15°
M	0.25	1.02	0.010	0.040

NOTES:

- LEADS WITHIN 0.25 mm (0.010) DIA., TRUE POSITION AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
- DIM L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIM A AND B INCLUDES MENISCUS.

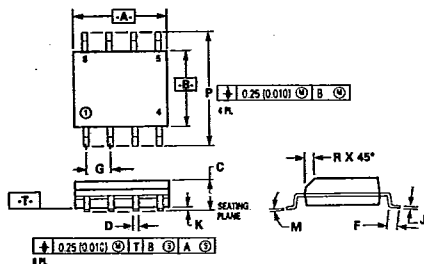


DIM	MIN	MAX	MIN	MAX
A	25.66	27.17	1.010	1.070
B	6.10	6.80	0.240	0.269
C	3.81	4.57	0.150	0.180
D	0.39	0.55	0.015	0.022
E	1.27 BSC		0.050 BSC	
F	1.27	1.77	0.050	0.070
G	2.54 BSC		0.100 BSC	
H	0.21	0.38	0.008	0.015
J	2.80	3.55	0.110	0.140
K	7.62 BSC		0.300 BSC	
L	0°	15°	0°	15°
M	0.51	1.01	0.020	0.040

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION "L" TO CENTER OF LEAD WHEN FORMED PARALLEL.
- DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.

D SUFFIX PLASTIC SOIC PACKAGE CASE 751-03

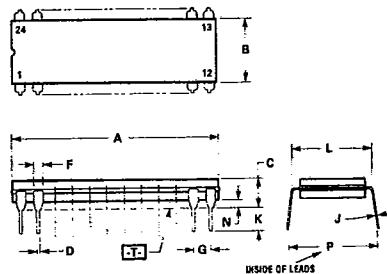


DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.196
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
E	0.40	1.25	0.016	0.049
F	1.27 BSC		0.050 BSC	
G	0.18	0.25	0.007	0.009
H	0.10	0.25	0.004	0.009
J	0°	7°	0°	7°
K	5.80	6.20	0.228	0.244
L	0.25	0.50	0.010	0.019

NOTES:

- DIMENSIONS "A" AND "B" ARE DATUMS AND "T" IS A DATUM SURFACE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIM: MILLIMETER.
- DIMENSION "A" AND "B" DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

L SUFFIX CERAMIC PACKAGE CASE 758-01

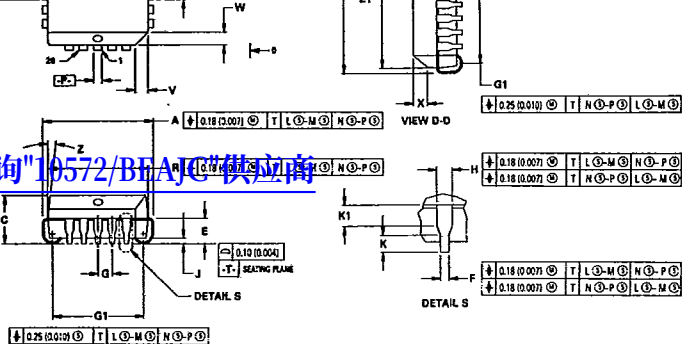


DIM	MIN	MAX	MIN	MAX
A	31.50	32.64	1.240	1.285
B	7.24	7.75	0.285	0.305
C	3.68	4.44	0.145	0.175
D	0.38	0.53	0.015	0.021
E	1.14	1.57	0.045	0.062
F	2.54 BSC		0.100 BSC	
G	0.20	0.33	0.008	0.013
H	2.54	4.19	0.100	0.165
J	7.62	7.87	0.300	0.310
K	0.51	1.27	0.020	0.050
L	9.14	10.16	0.350	0.400

NOTES:

- DIMENSION A IS DATUM.
- POSITIONAL TOLERANCE FOR LEADS: 24 PLACES $\pm 0.25 (0.010) \text{ T} \text{ A}$.
- L.T. IS SEATING PLANE.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1973.

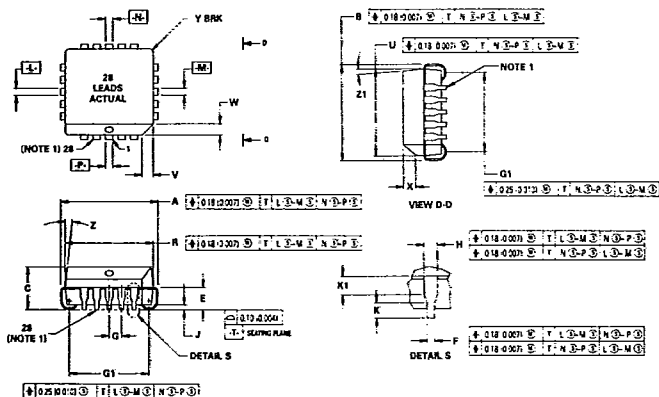
查询"10572/BEAJC"供应商



FN SUFFIX
PLASTIC PACKAGE
CASE 775-02

IS 0.25 (0.010) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.78	10.03	0.385	0.395
B	9.78	10.03	0.385	0.395
C	4.20	4.57	0.165	0.180
E	2.29	2.79	0.090	0.110
F	0.33	0.48	0.013	0.019
G	1.27 BSC		0.050 BSC	
H	0.66	0.81	0.026	0.032
J	0.51	—	0.020	—
K	0.64	—	0.025	—
R	8.89	9.04	0.350	0.356
U	8.89	9.04	0.350	0.356
V	1.07	1.21	0.042	0.048
W	1.07	1.21	0.042	0.048
X	1.07	1.42	0.042	0.056
Y	—	0.50	—	0.020
Z	2°	10°	2°	10°
G1	7.88	8.38	0.310	0.330
K1	1.02	—	0.040	—
Z1	2°	10°	2°	10°



FN SUFFIX
PLASTIC PACKAGE
CASE 776-02

- NOTES:
1. DUE TO SPACE LIMITATION, CASE 776-02 SHALL BE REPRESENTED BY A GENERAL (SMALLER) CASE OUTLINE DRAWING RATHER THAN SHOWING ALL 28 LEADS.
 2. DATUMS -L-, M-, N-, AND -P- DETERMINED WHERE TOP OF LEAD SHOULDER EXIT PLASTIC BODY AT MOLD PARTING LINE.
 3. DIM G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
 4. DIM R AND U DO NOT INCLUDE MOLD PROTRUSION; ALLOWABLE MOLD PROTRUSION IS 0.25 (0.010) PER SIDE.
 5. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 6. CONTROLLING DIMENSION: INCH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.32	12.57	0.485	0.495
B	12.32	12.57	0.485	0.495
C	4.20	4.57	0.165	0.180
E	2.29	2.79	0.090	0.110
F	0.33	0.48	0.013	0.019
G	1.27 BSC		0.050 BSC	
H	0.66	0.81	0.026	0.032
J	0.51	—	0.020	—
K	0.64	—	0.025	—
R	11.43	11.58	0.450	0.456
U	11.43	11.58	0.450	0.456
V	1.07	1.21	0.042	0.048
W	1.07	1.21	0.042	0.048
X	1.07	1.42	0.042	0.056
Y	—	0.50	—	0.020
Z	2°	10°	2°	10°
G1	10.42	10.92	0.410	0.430
K1	1.02	—	0.040	—
Z1	2°	10°	2°	10°

Surface Mount Packages allow more optimum device performance with the smaller Surface Mount configuration. Internal lead lengths, parasitic capacitance and inductance that placed limitations on chip performance have been reduced.

The lower profile of Surface Mount Packages allows more boards to be utilized in a given amount of space. They are stacked closer together and utilize less total volume than insertion populated PC boards.

Printed circuit costs are lowered with the reduction of the number of board layers required. The elimination or reduction of the number of plated through holes in the board, contribute significantly to lower PC board prices.

Surface Mount assembly does not require the preparation of components that are common on insertion technology lines. Surface Mount components are sent directly to the assembly line, eliminating an intermediate step.

Automatic placement equipment is available that can place Surface Mount components at the rate of a few thousand per hour to hundreds of thousands of components per hour.

Surface Mount Technology is cost effective, allowing the manufacturer the opportunity to produce smaller units and offer increased functions with the same size product.

MECL AVAILABILITY IN SURFACE MOUNT

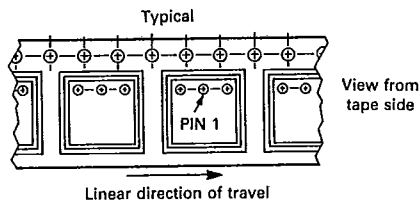
Motorola is now offering MECL 10K and MECL 10KH in the PLCC (Plastic Leaded Chip Carrier) packages.

MECL in PLCC may be ordered in conventional plastic rails or on Tape and Reel. Refer to the Tape and Reel section for ordering details.

TAPE AND REEL

Motorola has now added the convenience of Tape and Reel packaging for our growing family of standard Integrated Circuit products. The packaging fully conforms to

MECHANICAL POLARIZATION



ORDERING INFORMATION

- Minimum Lot Size/Device Type = 3000 Pieces.
- No Partial Reel Counts Available.
- To order devices which are to be delivered in Tape and Reel, add the appropriate suffix to the device number being ordered.

EXAMPLE:

ORDERING CODE

MC10100FN
MC10100FNR2
MC10H100FN
MC10H100FNR2
MC12015D
MC12015DR2

SHIPMENT METHOD

Magazines (Rails)
13 inch Tape and Reel
Magazines (Rails)
13 inch Tape and Reel
Magazines (Rails)
13 inch Tape and Reel

DUAL-IN-LINE PACKAGE TO PLCC PIN CONVERSION DATA

The following tables give the equivalent I/O pinouts of Dual-In-Line (DIL) packages and Plastic Leaded Chip Carrier (PLCC) packages.

Conversion Tables

16 PIN DIL	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
20 PIN PLCC	2	3	4	5	7	8	9	10	12	13	14	15	17	18	19	20

20 PIN DIL	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
20 PIN PLCC	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20

24 PIN DIL	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24
28 PIN PLCC	2	3	4	5	6	7	9	10	11	12	13	14	16	17	18	19	20	21	23	24	25	26	27	28